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By: May Beyma
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**IN THE UNITED STATES PATENT AND
TRADEMARK OFFICE**

Applicant: EMESH, Ismail et al Docket No.: 34759.9600
Serial No.: 09/781,593 Art Unit: 3723
Filing Date: 2/12/2001 Examiner: Unknown
TITLE: METHOD AND APPARATUS FOR ELECTROCHEMICAL PLANARIZATION
OF A WORKPIECE

10/19/2001 SZEWDIE1 00000002 09781593

01 FC:102
02 FC:103

252.00 OP
144.00 OP

PRELIMINARY AMENDMENT

Assistant Commissioner
for Patents
Box AMENDMENT-FEE
Washington, D.C. 20231

Dear Madam or Sir:

10/17/2001 SZEWDIE1 00000094 09781593

01 FC:102
02 FC:103

Adjustment date: 10/19/2001 SZEWDIE1
10/17/2001 SZEWDIE1 00000094 09781593

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TC 1700

Prior to the examination of the above-identified application, please enter the following amendments:

IN THE SPECIFICATION

Please replace the paragraph beginning at page 8, line 24, with the following rewritten paragraph:

--The electrolytic planarizing solution may also include a film forming agent which includes any compound or mixture of compounds that facilitates the formation of a passivation film of metal oxides and dissolution-inhibiting layers on the metallized surface of wafer 60. The passivation film reduces, and preferably eliminates, wet etching of the low topography areas of the metallized surface 80 of wafer 60 until the low topography areas come in contact with polishing pad 40. When these low topography areas come in contact with polishing pad 40 and electrical conductors 70, described below, the passivation film is removed and electrochemical etching may proceed. Thus, the passivation film enhances uniform planarization of wafer 60. Suitable film forming agents may be formed of nitrogen-containing cyclic compounds such as proline, adedine, mercaptonitriles, imidazole, triazole, quinaldic acid, benzotriazole,